Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **1A**
2. **1Y**
3. **2A**
4. **2Y**
5. **3A**
6. **3Y**
7. **GND**
8. **4Y**
9. **4A**
10. **5Y**
11. **5A**
12. **6Y**
13. **6A**
14. **VCC**

**.043”**

**S 04**

**A**

**MASK**

**REF**

**.043”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .003” X .003”**

**Backside Potential:**

**Mask Ref: S 04 A**

**APPROVED BY: DK DIE SIZE .043” X .043” DATE: 9/22/21**

**MFG: NATIONAL THICKNESS .015” P/N: 54S04**

**DG 10.1.2**

#### Rev B, 7/1